

27HC256

256K (32K x 8) High-Speed CMOS EPROM

FEATURES

- · High speed performance
 - 55 ns access time available
- · CMOS Technology for low power consumption
 - 55 mA Active current
- 100 µA Standby current
- · OTP (one time programming) available
- · Auto-insertion-compatible plastic packages
- · Auto ID aids automated programming
- · Organized 32K x 8: JEDEC standard pinouts
 - 28-pin Dual-in-line and SOIC package
 - 32-pin Chip carrier (leadless or plastic)
 - 28-pin Very Small Outline Package (VSOP)
- Available for the following temperature ranges:

- Commercial:

0°C to +70°C

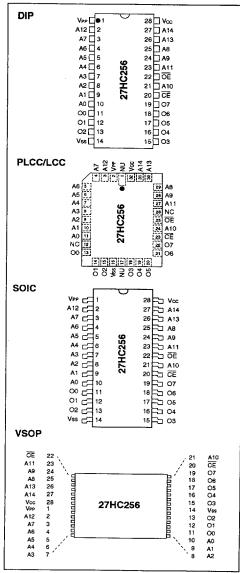
- Industrial:

-40°C to +85°C -40°C to +125°C

DESCRIPTION

The Microchip Technology Inc. 27HC256 is a CMOS 256K bit electrically Programmable Read Only Memory (EPROM). The device is organized as 32K words of 8 bits each. Advanced CMOS technology allows bipolar speed with a significant reduction in power. A low power option (L) allows further reduction in the standby power requirement to 100 µA The 27HC256 is configured in a standard 256K EPROM pinout which allows an easy upgrade for present 27C256 users. A complete family of packages are offered to provide the utmost flexibility. The 27HC256 allows high performance microprocessors to run at full speed without the need of wait states. CMOS design and processing makes this part suitable for applications where high reliability and reduced power consumption are essential

PACKAGE TYPE



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1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

Vcc and input voltages w.r.t. Vss.....-0.6V to +7.25V

VPP voltage w.r.t. Vss during
programming....-0.6V to +14V

Voltage on A9 w.r.t. Vss...-0.6V to +13.5V

Output voltage w.r.t. Vss...-0.6V to Vcc +1.0V

Temperature under bias...-65°C to +125°C

Storage temperature...-65°C to +150°C

Maximum exposure to UV.....7258Wsec/cm²

ESD protection on all pins.....2 KV

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0-A14	Address Inputs
CE	Chip Enable
ŌĒ	Output Enable
VPP	Programming Voltage
00 - 07	Data Output
Vcc	+5V
Vss	Ground
NC	No Connection; No Internal Connection
NU	Not Used; No External Connection Is Allowed

TABLE 1-2: READ OPERATION DC CHARACTERISTICS

			Com Indu	= +5V nmercia strial: nded (-	Tamb = 0°C to +70°C Tamb = -40°C to +85°C Tamb = -40°C to +125°C		
Parameter	Part*	Status	Symbol	Min	Max	Units	Conditions		
Input Voltages	all	Logic "1" Logic "0"	VIH VIL	2.0 -0.1	Vcc+1 0.8	V V			
Input Leakage	all		lu	-10	10	μΑ	Vin = -0.1V to Vcc +1.0V		
Output Voltages	all	Logic "1" Logic "0"	Voh Vol	2.4	0.45	V V	IOH = -4 μA IOL = 16 mA		
Output Leakage	all	_	ILO	-10	10	μА	Vout = -0.1V to Vcc +0.1V		
Input Capacitance	all	-	Cin	_	6	pF	Vin = 0V; Tamb = 25°C; f = 1 MHz		
Output Capacitance	all		Соит		12	pF	Vout = 0V; Tamb = 25°C; f = 1 MHz		
Power Supply Current, Active	C I,E	TTL input TTL input	ICC1 ICC2	_	55 65	mA mA	VCC = 5.5V; VPP = VCC f = 2 MHz; \overline{OE} = \overline{CE} = ViL; lout = 0 mA; ViL = -0.1 to 0.8V; ViH = 2.0 to VCC; Note 1		
Power Supply Current, Standby, Std	C I,E	_	Icc(s)1	-	35 40	mA mA			
Power Supply Current, Standby, "L" version (low power)	C I,E I,E	TTL input TTL input CMOS input	ICC(S)2	_	2 3 100	mA mA μA	CE = Vcc ± 0.2V		
IPP Read Current VPP Read Voltage	all all	Read Mode Read Mode	IPP VPP	Vcc -0.7	100 Vcc	μA V	VPP = 5.5V Note 2		

^{*} Parts: C=Commercial Temperature Range; L = Low Power; I, E=Industrial and Extended Temperature Ranges

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Note 1: Active current increases 3 mA per MHz for Commercial part or 5mA per MHz for Industrial or Extended

temperature parts up to operating frequency.

Note 2: Vcc must be applied simultaneously or before VPP, and be removed simultaneously or after VPP.

TABLE 1-3: READ OPERATION AC CHARACTERISTICS

AC Testing Waveform: VIH = 3.0V and VIL = 0.0V; VOH = VOL = 1.5VOutput Load: 1 TTL Load + 30 pF

Input Rise and Fall Times: 5 ns

Ambient Temperature: Commercial:

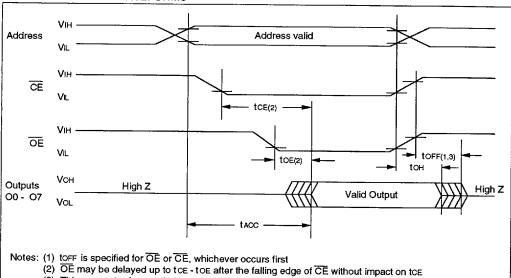
Tamb = $0^{\circ}C$ to $+70^{\circ}C$ Tamb = -40° C to $+85^{\circ}$ C

Industrial: Extended (Automotive): 4000 to .4000

Extended (Automotive): Tamb = -40°C to +125°C											
Parameter	Part*	Sym	27HC256-55		27HC256-70		27HC256-90				
		Sylli	Min	Min Max		Max	Min	Max	Units	Conditions	
Address to Output Delay	all	tacc	_	55	_	70	_	90	ns	CE = OE = Vil	
CE to Output Delay	L S	tCE1 tCE2	_	55 45	_	70 45	_	90 50	ns	OE = VIL	
OE to Output Delay	all	toe	_	30	_	35		40	ns	CE = VIL	
OE to O/P High Impedance	all	toff	0	25	0	30	0	35	ns		
Output Hold from Address CE or OE, whichever goes first	all	tон	0	_	0	_	0	_	ns		

^{*} Parts: S = Standard Power; L = Low Power

FIGURE 1-1: **READ WAVEFORMS**



(3) This parameter is sampled and is not 100% tested.

PROGRAMMING DC CHARACTERISTICS **TABLE 1-4:**

	***		Ambient Temperature: Tamb = 25° C $\pm 5^{\circ}$ C VCC = 6.5 V ± 0.25 V, VPP = VH = 13.0 V ± 0.25 V							
Parameter	Status	Symbol	Min	Max.	Units	Conditions				
Input Voltages	Logic"1" Logic"0"	VIH VIL	2.0 -0.1	Vcc+1 0.8	V V					
Input Leakage	_	lLi .	-10	10	μΑ	VIN = 0V to VCC				
Output Voltages	Logic"1" Logic"0"	Voh Vol	2.4	 0.45	V V	IOH = -4 mA IOL = 16 mA				
Vcc Current, program & verify	_	lcc		55	mA					
VPP Current, program	_	IPP		30	mA	Note 1				
A9 Product Identification	_	Vн	11.5	12.5	٧					

Note 1: Vcc must be applied simultaneously or before VPP and removed simultaneously or after VPP

PROGRAMMING AC CHARACTERISTICS **TABLE 1-5:**

for Program, Program Verify and Program Inhibit Modes AC Testing Waveform: VIH=2.4V and VIL=0.45V; VOH=2.0V; VOL=0.8V Ambient Temperature: Tamb=25°C ± 5°C VCC= 6.5V ± 0.25V, VPP =13.0V ± 0.25V									
Parameter		Symbol	Min.	Max.	Units	Remarks			
Address Set-Up Time		tas	2		μs				
Data Set-Up Time		tos	2	_	μs				
Data Hold Time		tDH	2		μs				
Address Hold Time		tAH	0		μs				
Float Delay (2)		tDF	0	130	ns				
Vcc Set-Up Time		tvcs	2		μs				
Program Pulse Width (1)		tpw	95	105	μs	100 μs typical			
OE Set-Up Time		toes	2	_	μs				
VPP Set-Up Time		tvps	2		μs				
Data Valid from OE		toE		100	ns				

Note 1: For express algorithm, initial programming width tolerance is 100 μs $\pm 5\%.$

Note 2: This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

FIGURE 1-2: PROGRAMMING WAVEFORMS

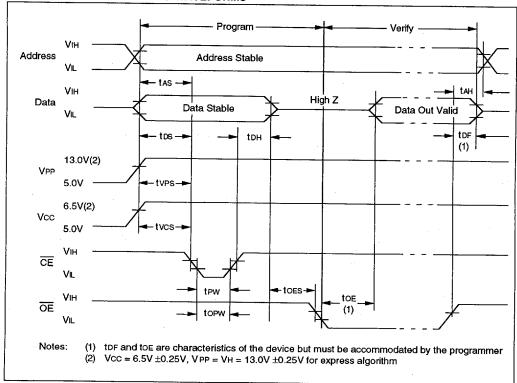


TABLE 1-6: MODES

Operation Mode	CE	ŌĒ	VPP	A9	00 - 07		
Read	VIL	VIL	VIL VCC		Dout		
Program	VIL	ViH	VH	X	DIN		
Program Verify	ViH	VIL	VH	Х	Douт High Z		
Program Inhibit	ViH	ViH	VH X	Х			
Standby	ViH	Х	Vcc	х	High Z		
Output Disable	VIL	ViH	Vcc	х	High Z		
Identity	VIL	VIL	Vcc	VH	Identity Code		

X = Don't Care

2.0 FUNCTIONAL DESCRIPTION

The 27HC256 has the following functional modes:

- Operation: The 27HC256 can be activated for data read, be put in standby mode to lower its power consumption, or have the outputs disabled.
- Programming: To receive its permanent data, the 27HC256 must be programmed. Both a program and program/verify procedure are available. It can be programmed with the "Express" algorithm.

The programming equipment can automatically recognize the device type and manufacturer using the identity mode.

2.1 Operations

- Read
- Standby
- Output Disable

For the general characteristics in these operation modes, refer to the table above.

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2.2 Read Mode

For timing and AC characteristics refer to the tables Read Waveforms and Read Operation AC Characteristics

The 27HC256's memory data is accessed when

- the chip is enabled by setting the CE pin low.
- the data is gated to the output pins by setting the OE pin low

For Read operations on the Low Power version, once the addresses are stable, the address access time (tAcc) is equal to the delay from \overline{CE} to output (tCE). A faster \overline{CE} access time (tCE) is available on the standard part to provide the additional time for decoding the \overline{CE} signal. Data is transferred to the output after a delay (tOE) from the falling edge of \overline{OE}

2.3 Standby Mode

The standby mode is entered when the $\overline{\text{CE}}$ pin is high, and a program mode is not defined. When these conditions are met, the supply current will drop from 55 mA to 100 μA on the low power part, and to 35 mA on the standard part.

2.4 Output Disable

This feature eliminates bus contention in multiple bus microprocessor systems. The outputs go to a high impedance when the $\overline{\text{OE}}$ pin is high, and the program mode is not defined.

2.5 Programming Algorithms

The Express algorithm has been developed to improve programming throughput times in a production environment. Up to 10 pulses of 100 µs each are applied until the byte is verified. No over-programming is required. A flowchart of this algorithm is shown in Figure 2-1.

The programming mode is entered when:

- a) Vcc is brought to the proper level
- b) VPP is brought to the proper VH level
- c) the OE pin is high
- d) the CE pin is low

Since the erased state is "1" in the array, programming of "0" is required. The address of the memory location to be programmed is set via pins A0 - A14, and the data is presented to pins O0 - O7. When data and address are stable, a low going pulse on the \overline{CE} line programs that memory location.

2.6 <u>Verify</u>

After the array has been programmed, it must be verified to make sure that all the bits have been correctly programmed. This mode is entered when all of the following conditions are met:

- a) Vcc is at the proper level
- b) VPP is at the proper VH level
- c) the CE pin is high
- d) the OE line is low

After the array has been programmed it must be verified to ensure all the bits have been correctly programmed. This mode is entered when all the following conditions are met:

- a) Vcc is at the proper level
- b) VPP is at the proper VH level,
- c) the CE line is high, an
- d) the OE line is low.

2.7 Inhibit Mode

When Programming multiple devices in parallel with different data only \overline{CE} needs to be under separate control to each device. By pulsing the \overline{CE} line low on a particular device, that device will be programmed, and all other devices with \overline{CE} held high will not be programmed with the data although address and data are available on their input pins.

2.8 <u>Identity Mode</u>

In this mode specific data is read from the device that identifies the manufacturer as Microchip Technology, and the device type. This mode is entered when pin A9 is taken to VH (11.5V to 12.5V). The TE and TE pins must be at VII. A0 is used to access any of the two non-erasable bytes whose data appears on O0 - O7.

Pin -	Input	Output									
Identity	Α0	0	0 6	O 5	0	0	0	_	00	H	
▼			L		L	_				x	
Manufacturer Device Type*	VIL VIH	0	0	1	0	1	0 1	0	1 0	29 94	

2.9 Erasure

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all "1"s state when exposed to ultraviolet light at wavelengths ≤ 4000 Angstroms (Å). The recommended procedure is to expose the erasure window of device to a commercial UV source emitting at 2537 Å with an intensity of 12,000µW/cm² at 1". The erasure time at that distance is about 15 to 20 min.

Note: Fluorescent lights and sunlight emit rays at the specified wavelengths. The erasure time is about 3 years or 1 week resp. in these cases. To prevent loss of data, an opaque label should be placed over the erasure window.

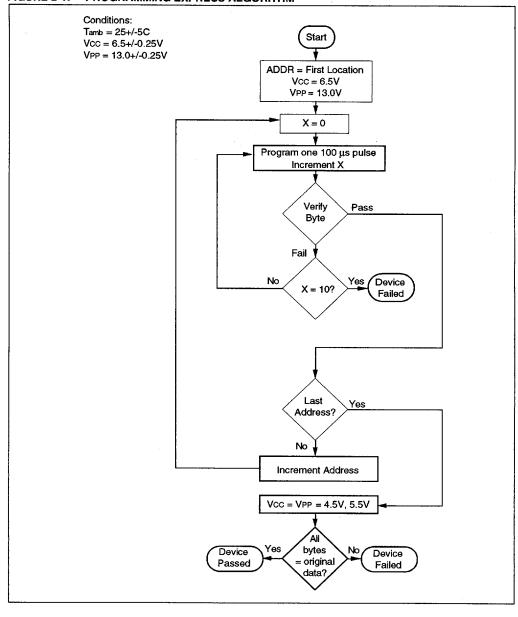
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FIGURE 2-1: PROGRAMMING EXPRESS ALGORITHM



27HC256 Product Identification System

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

